INTEGRATED CIRCUITS



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Video processor with automatic cut-off control

FEATURES

- Operates from an 8 V DC supply
- Black level clamping of the colour difference, luminance and RGB input signals with coupling-capacitor DC level storage
- Two analog RGB inputs, selected either by fast switch signals or the I²C-bus; brightness and contrast control of these RGB inputs
- Saturation, contrast, brightness and white adjustment via I²C-bus
- Same RGB output black levels for Y/CD and RGB input signals
- Timing pulse generation from either a 2- or 3-level sandcastle pulse for clamping, vertical synchronization and cut-off timing pulses
- Automatic cut-off control or clamped output selectable via I²C-bus
- Automatic cut-off control with picture tube leakage current compensation
- Cut-off measurement pulses after end of the vertical blanking pulse or end of an extra vertical flyback pulse
- Two switch-on delays to prevent discolouration before steady-state operation
- Average beam current and peak drive limiting
- PAL/SECAM or NTSC matrix selection via I²C-bus
- Emitter-follower RGB output stages to drive the video output stages
- I²C-bus controlled DC output e. g. for hue-adjust of NTSC (multistandard) decoders

GENERAL DESCRIPTION

The TDA4685 is a monolithic, integrated circuit with a luminance and a colour difference interface for video processing in TV receivers.

Its primary function is to process the luminance and colour difference signals from a colour decoder which is equipped e. g. with the multistandard decoder TDA4655 or TDA9160 plus delayline TDA4661 and the Picture Signal



Improvement (PSI) IC TDA467X or from a Feature Module. The required input signals are:

- · luminance and negative colour difference signals
- 2- or 3-level sandcastle pulse for internal timing pulse generation
- I²C-bus data and clock signals for microprocessor control.

Two sets of analog RGB colour signals can also be inserted, e.g. one from a peritelevision connector and the other from an on-screen display generator. The TDA4685 has I²C-bus control of all parameters and functions with automatic cut-off control of the picture tube cathode currents. It provides RGB output signals for the video output stages.

The TDA4685 is a simplified, pin compatible (except pin 18) version of the TDA4680. The module address via the I^2C -bus can be used for both ICs; where a function is not included in the TDA4685 then the I^2C -bus command is not executed. The differences with the TDA4680 are:

- no automatic white level control; the white levels are determined directly by the l²C-bus data
- RGB reference levels for automatic cut-off control are not adjustable via I²C-bus
- · clamping delay is fixed
- only contrast and brightness adjust for the RGB input signals
- the measurement lines are triggered either by the trailing edge of the vertical component of the sandcastle pulse or by the trailing edge of an optional external vertical flyback pulse (on pin 18), according to which occurs first.

The TDA4686 is like TDA4685 but intended for double line frequency application.

TDA4685

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
VP	supply voltage (pin 5)	7.2	8.0	8.8	V
I _P	supply current (pin 5)	_	60	-	mA
V _{8(p-p)}	luminance input (peak-to-peak value)	_	0.45	-	V
V _{6(p-p)}	–(B–Y) input (peak-to-peak value)	_	1.33	-	V
V _{7(p-p)}	-(R-Y) input (peak-to-peak value)	_	1.05	-	V
V ₁₄	three-level sandcastle pulse				
	H +V	_	2.5	-	V
	н	_	4.5	-	V
	ВК	_	8.0	-	V
	two-level sandcastle pulse				
	H + V	_	2.5	-	V
	ВК	_	4.5	-	V
Vi	RGB input signals at pins 2, 3, 4, 10, 11 and 12 (black-to-white value)	_	0.7	-	V
V _{o(p-p)}	RGB outputs at pins 24, 22 and 20 (peak-to-peak value)	_	2.0	-	V
T _{amb}	operating ambient temperature	0	-	+70	°C

ORDERING INFORMATION

EXTENDED	PACKAGE					
TYPE NUMBER	PINS	PIN POSITION	MATERIAL	CODE		
TDA4685	28	DIL	plastic	SOT117 ⁽¹⁾		

Note

1. SOT117-1; 1996 November 25.

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PINNING

SYMBOL	PIN	DESCRIPTION			
FSW ₂	1	fast switch 2 input			
R ₂	2	red input 2			
G ₂	3	green input 2			
B ₂	4	blue input 2			
V _P	5	supply voltage			_
–(B–Y)	6	colour difference input –(B–Y)	FSW ₂	U	28 SCL
–(R–Y)	7	colour difference input –(R–Y)	R ₂ 2		27 SDA
Y	8	luminance input			26 HUE
GND	9	ground	G ₂ 3		
R ₁	10	red input 1	B ₂ 4		25 C _R
G ₁	11	green input 1	V _P 5		24 R _O
B ₁	12	blue input 1	–(B–Y) 6		23 C _G
FSW ₁	13	fast switch 1 input	-(R-Y) 7		22 G _O
SC	14	sandcastle pulse input	Y 8	TDA4685	21 C _B
BCL	15	average beam current limiting input	GND 9		20 B _O
C _{PDL}	16	storage capacitor for peak drive limiting			19 CI
CL	17	storage capacitor for leakage current	R ₁ 10		
V _{FB}	18	vertical flyback pulse input	G ₁ 11		18 V _{FB}
CI	19	cut-off measurement input	B ₁ 12		17 C _L
B _O	20	blue output	FSW ₁ 13		16 C _{PDL}
C _B	21	blue cut-off storage capacitor	SC 14		15 BCL
G _O	22	green output		MED709	9
C _G	23	green cut-off storage capacitor			
R _O	24	red output			
C _R	25	red cut-off storage capacitor			
HUE	26	hue control output			
SDA	27	I ² C-bus serial data input / acknowledge output	Fig 2	Pin configur	ation.
SCL	28	I ² C-bus serial clock input		coringui	

I²C-BUS CONTROL

The I²C-bus transmitter provides the data bytes to select and adjust the following functions and parameters:

- brightness adjust
- saturation adjust
- contrast adjust
- DC output e. g. for hue control
- RGB gain adjust
- peak drive limiting level adjust
- selects either 3-level or 2-level (5 V) sandcastle pulse
- enables cut-off control / enables output clamping
- selects either PAL/SECAM or NTSC matrix
- enables/disables synchronization of the execution of l²C-bus commands with the vertical blanking interval
- enables Y-CD, RGB1 or RGB2 input.

I²C-BUS TRANSMITTER AND DATA TRANSFER

I²C-bus specification

The I²C-bus is a bi-directional, two-wire, serial data bus for intercommunication between ICs in an equipment. The microcontroller transmits data to the I²C-bus receiver in the TDA4685 over the serial data line SDA (pin 27) synchronized by the serial clock line SCL (pin 28). Both lines are normally connected to a positive voltage supply through pull-up resistors. Data is transferred when the SCL line is LOW. When SCL is HIGH the serial data line SDA must be stable. A HIGH-to-LOW transition of the SDA line when SCL is HIGH is defined as a start bit. A LOW-to-HIGH transition of the SDA line when SCL is HIGH is defined as a stop bit. Each transmission must start with a start bit and end with a stop bit. The bus is busy after a start bit and is only free again after a stop bit has been transmitted.

Preliminary specification

TDA4685

I²C-bus receiver

(microcontroller write mode) Each transmission to the l²C-bus receiver consists of at least three bytes following the start bit. Each byte is acknowledged by an acknowledge bit immediately following each byte. The first byte is the Module ADdress (MAD) byte, also called slave address byte. This includes the module address, 1000100₂ for the TDA4685. The TDA4685 is a slave receiver (R/W = 0), therefore the module address byte is 10001000₂ (88 Hex), see Fig.3.

The length of a data transmission is unrestricted, but the module address and the correct sub-address must be transmitted before the data byte(s). The order of data transmission is shown in Fig.4 and Fig.5. Without auto-increment (BREN = 0 or 1) the Module ADdress (MAD) byte is followed by a Sub-ADdress (SAD) byte and one data byte only (Fig.4).

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Auto-increment

The auto-increment format enables guick slave receiver initialization by one transmission, when the I²C-bus control bit BREN = 0 (see control register bits of Table 1). If BREN = 1 auto-increment is not possible. If the auto-increment format is selected, the MAD byte is followed by an SAD byte and by the data bytes of consecutive sub-addresses (Fig.5). All sub-addresses from 00 to 0F are automatically incremented, the sub-address counter wraps round from 0F to 00. Reserved sub-addresses 07, 08, 09, 0B, 0E and 0F are treated as legal but have no effect. Sub-addresses outside the range 00 and 0F are not acknowledged by the device. The sub-addresses are stored in the TDA4685 to address the following parameters and functions, see Table 1:

- brightness adjust
- saturation adjust
- · contrast adjust
- hue control voltage
- RGB gain adjust
- · peak drive limiting adjust
- control register functions.

The data bytes (D7-D0 of Table 1) provide the data of the parameters and functions for video processing.

Control register 1

NMEN (NTSC-Matrix ENable): 0 = PAL/SECAM matrix

1 = NTSC matrix.

BREN (Buffer Register ENable):

0 = new data is executed as soon as it is received

1 = data is stored in buffer registers and is transferred to the data registers during the next vertical blanking interval. The I²C-bus receiver does not accept any new data until this data is transferred into the data registers.

SC5 (SandCastle 5 V):

- 0 = 3-level sandcastle pulse
- 1 = 2-level (5 V) sandcastle pulse.

Control register 2

FSON2 - Fast Switch 2 ON FSDIS2 - Fast Switch 2 DISable FSON1 - Fast Switch 1 ON FSDIS1 - Fast Switch 1 DISable The RGB input signals are selected by FSON2 and FSON1 or FSW₂ and FSW₁:

- FSON2 has priority over FSON1;
- FSW₂ has priority over FSW₁;

• FSDIS1 and FSDIS2 disable FSW₁ and FSW₂ (see Table 2).

BCOF - Black level Control OFf:

0 = automatic cut-off control enabled

1 = automatic cut-off control disabled; RGB outputs are clamped to fixed DC levels.

When the supply voltage has dropped below approximately 6.0 V (usually occurs when the TV receiver is switched on or the supply voltage is interrupted) all data and function bits are set to $01_{\text{Hex.}}$

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FUNCTION	SAD	MSB			DATA	BYTE			LSB
FUNCTION	(HED)	7	6	5	4	3	2	1	0
Brightness	00	0	0	A05	A04	A03	A02	A01	A00
Saturation	01	0	0	A15	A14	A13	A12	A11	A10
Contrast	02	0	0	A25	A24	A23	A22	A21	A20
Hue control voltage	03	0	0	A35	A34	A33	A32	A31	A30
Red gain	04	0	0	A45	A44	A43	A42	A41	A40
Green gain	05	0	0	A55	A54	A53	A52	A51	A50
Blue gain	06	0	0	A65	A64	A63	A62	A61	A60
Reserved	07	0	0	x	x	х	х	х	х
Reserved	08	0	0	x	x	х	х	х	х
Reserved	09	0	0	х	х	х	х	х	х
Peak drive limit	0A	0	0	AA5	AA4	AA3	AA2	AA1	AA0
Reserved	0B	х	x	x	x	x	х	х	х
Control register 1	0C	SC5	х	BREN	x	NMEN	х	х	х
Control register 2	0D	х	x	x	BCOF	FSDIS2	FSON2	FSDIS1	FSON1
Reserved	0E	х	x	x	x	х	х	х	х
Reserved	0F	х	x	x	x	x	x	х	х

Table 1Sub-address (SAD) and data bytes(1).

Note to Table 1

1. X is 'don't care', but for software compatibility with other or future video ICs it is recommended to set all 'X' to '0'.

 Table 2
 Signal input selection by the fast source switches⁽¹⁾.

l ² C	BUS CONT	ROL BITS		ANALOG SW	TCH SIGNALS	INF	TED	
FSON2	FSDIS2	FSON1	FSDIS1	FSW ₂ (pin 1)	FSW ₁ (pin 13)	RGB ₂	RGB ₁	Y/CD
L	L	L	L	L	L			ON
				L	н		ON	
				Н	Х	ON		
L	L	L	Н	L	Х			ON
				Н	Х	ON		
L	L	н	Х	L	Х		ON	
				Н	Х	ON		
L	н	L	L	Х	L			ON
				Х	Н		ON	
L	Н	L	Н	Х	Х			ON
L	Н	Н	Х	Х	Х		ON	
Н	Х	Х	Х	Х	Х	ON		

Note to Table 2

1. Where L is a logic LOW (< 0.4 V), H is a logic HIGH (> 0.9 V), X is 'don't care', and ON is the selected input signal.

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V _P	supply voltage (pin 5)	-	8.8	V
VI	input voltage (pins 1 to 8, 10 to 13, 16, 21, 23 and 25)	-0.1	VP	V
	input voltage (pins 15, 18 and 19)	-0.7	V _P + 0.7	V
	input voltage (pins 27 and 28)	-0.1	8.8	V
V ₁₄	sandcastle pulse voltage	-0.7	V _P +5.8	V
I _{AV}	average current (pins 20, 22 and 24)	-10	4	mA
I _M	peak current (pins 20, 22 and 24)	-20	4	mA
I ₂₆	output current	-8	0.6	mA
T _{stg}	storage temperature	-20	+150	°C
T _{amb}	operating ambient temperature	0	+70	°C
P _{tot}	total power dissipation	-	1.2	W



CHARACTERISTICS

All voltages are measured in test circuit of Fig.7 with respect to GND (pin 9); V_P = 8.0 V; T_{amb} =+25 °C:

- at nominal signal amplitudes (black-to-white) at output pins 24, 22 and 20,

- at nominal settings of brightness, contrast, saturation and white level control,

- without beam current or peak drive limiting; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
VP	supply voltage (pin 5)		7.2	8.0	8.8	V
I _P	supply current (pin 5)		-	60	-	mA
Colour dif	ference inputs		•	•		
V _{6(p-p)}	–(B–Y) input (peak-to-peak value)	notes 1 and 2	-	1.33	-	V
V _{7(p-p)}	–(R–Y) input (peak-to-peak value)	notes 1 and 2	-	1.05	-	V
V _{6,7}	internal DC bias voltage	at black level clamping	-	4.1	_	V
I _{6,7}	input current	during line scan	-	-	±0.1	μA
		at black level clamping	±100	-	-	μA
R _{6,7}	input resistance		10	-	-	MΩ
Luminanc	e/sync (VBS)					
V _{i(p-p)}	luminance input at pin 8 (peak-to-peak value)	note 2	-	0.45	-	V
V ₈	internal DC bias voltage	at black level clamping	-	4.1	-	V
I ₈	input current	during line scan	-	-	±0.1	μA
		at black level clamping	±100	-	_	μA
R ₈	input resistance		10	-	-	MΩ
R ₁ ,G ₁ and	B ₁ inputs		•	•		
V _{i(p-p)}	black-to-white input signals at pins 10, 11 and 12 (peak-to-peak value)	note 2	-	0.7	-	V
V _{10/11/12}	internal DC bias voltage	at black level clamping	-	5.7	-	V
I _{10/11/12}	input current	during line scan	-	-	±0.1	μA
		at black level clamping	±100	-	-	μA
R _{10/11/12}	input resistance		10	-	-	MΩ
R ₂ , G ₂ and	B ₂ inputs		•	•	1	
V _{i(p-p)}	black-to-white input signals at pins 2, 3 and 4 (peak-to-peak value)	note 2	-	0.7	-	V
V _{2/3/4}	internal DC bias voltage	at black level clamping	-	5.7	-	V
I _{2/3/4}	input current	during line scan	-	-	±0.1	μA
		at black level clamping	±100	-	_	μA
R _{2/3/4}	input resistance		10	-	_	MΩ
PAL/SECA	AM and NTSC matrix (note 3)					
	PAL/SECAM matrix	control bit NMEN = 0				
	NTSC matrix	control bit NMEN = 1				1

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
-	al switch FSW ₁ to select Y, CD or R ₁ , G ₁ s FSDIS1, FSON1 (see Table 2)	, B ₁ inputs	ļ	1		1
V ₁₃	voltage to select Y and CD			_	0.4	V
V 13	voltage range to select R_1 , G_1 , B_1		0.9	-	5.0	V
R ₁₃	internal resistance to ground		- 0.3	4.0		kΩ
Δt	difference between transit times for signal switching and signal insertion		-	-	10	ns
-	al switch FSW ₂ to select Y, CD / R ₁ , G ₁ , s FSDIS2, FSON2 (see Table 2)	$B_1 \text{ or } R_2, G_2, B_2 \text{ inputs}$				
V ₁	voltage to select Y, CD/R ₁ , G ₁ , B ₁		_	_	0.4	V
	voltage range to select R ₂ , G ₂ , B ₂		0.9	_	5.0	V
R ₁	internal resistance to ground		_	4.0	_	kΩ
Δt	difference between transit times for signal switching and signal insertion		-	-	10	ns
sub-addres data byte 3 data byte 2	$R-Y$) and $-(B-Y)$ signals under I ² C-bus coss 01 _{Hex} (bit resolution 1.5% of maximum $3F_{Hex}$ for maximum saturation 23 _{Hex} for nominal saturation 00_{Hex} for minimum saturation					
sub-addres data byte 3	ss 01_{Hex} (bit resolution 1.5% of maximum 3F _{Hex} for maximum saturation					
sub-addre data byte 2 data byte 2 data byte 0	ss 01_{Hex} (bit resolution 1.5% of maximum $3F_{Hex}$ for maximum saturation 23_{Hex} for nominal saturation 00_{Hex} for minimum saturation	saturation);		5	_	dB
sub-addre data byte 3 data byte 2 data byte 0	ss 01 _{Hex} (bit resolution 1.5% of maximum 3F _{Hex} for maximum saturation 23 _{Hex} for nominal saturation	saturation); at 23 _{Hex}	-	5		dB dB
sub-addres data byte 3 data byte 2	ss 01 _{Hex} (bit resolution 1.5% of maximum 3F _{Hex} for maximum saturation 23 _{Hex} for nominal saturation 00 _{Hex} for minimum saturation saturation below maximum	saturation);	-	5 50	-	•••=
sub-addres data byte 2 data byte 2 data byte 0 ds Contrast a acts on int sub-addres data byte 2 data byte 2 data byte 0	ss 01 _{Hex} (bit resolution 1.5% of maximum 3F _{Hex} for maximum saturation 23 _{Hex} for nominal saturation 00 _{Hex} for minimum saturation saturation below maximum adjust ernal RGB signals under I ² C-bus control, ss 02 _{Hex} (bit resolution 1.5% of maximum 3F _{Hex} for maximum contrast 22 _{Hex} for nominal contrast 00 _{Hex} for minimum contrast	saturation); at 23 _{Hex} at 00 _{Hex} ; f = 100 kHz contrast);	-	50	-	dB
sub-addres data byte 2 data byte 2 data byte 0 ds Contrast a acts on int sub-addres data byte 2 data byte 2 data byte 0	ss 01 _{Hex} (bit resolution 1.5% of maximum 3F _{Hex} for maximum saturation 23 _{Hex} for nominal saturation 00 _{Hex} for minimum saturation saturation below maximum adjust ernal RGB signals under I ² C-bus control, ss 02 _{Hex} (bit resolution 1.5% of maximum 3F _{Hex} for maximum contrast 22 _{Hex} for nominal contrast	saturation); at 23_{Hex} at 00_{Hex} ; f = 100 kHz contrast); at 22_{Hex}	- -	50		dB
sub-addres data byte 2 data byte 2 data byte 0 ds Contrast a acts on int sub-addres data byte 2 data byte 2 data byte 0 d _c	ss 01 _{Hex} (bit resolution 1.5% of maximum 3F _{Hex} for maximum saturation 23 _{Hex} for nominal saturation 00 _{Hex} for minimum saturation saturation below maximum adjust ernal RGB signals under I ² C-bus control, ss 02 _{Hex} (bit resolution 1.5% of maximum 3F _{Hex} for maximum contrast 22 _{Hex} for nominal contrast 00 _{Hex} for minimum contrast contrast below maximum	saturation); at 23 _{Hex} at 00 _{Hex} ; f = 100 kHz contrast);	- -	50	- 	dB
sub-addres data byte 2 data byte 2 data byte 2 data byte 2 data byte 2 acts on int sub-addres data byte 2 data byt	ss 01 _{Hex} (bit resolution 1.5% of maximum 3F _{Hex} for maximum saturation 23 _{Hex} for nominal saturation 00 _{Hex} for minimum saturation saturation below maximum adjust ernal RGB signals under I ² C-bus control, ss 02 _{Hex} (bit resolution 1.5% of maximum 3F _{Hex} for maximum contrast 22 _{Hex} for nominal contrast 00 _{Hex} for minimum contrast contrast below maximum	saturation); at 23_{Hex} at 00_{Hex} ; f = 100 kHz contrast); at 22_{Hex} at 00_{Hex}	- - - -	50		dB
sub-addres data byte 2 data byte 2 data byte 2 data byte 2 data byte 2 acts on int sub-addres data byte 2 data byt	ss 01 _{Hex} (bit resolution 1.5% of maximum BF _{Hex} for maximum saturation 23 _{Hex} for nominal saturation 20 _{Hex} for minimum saturation saturation below maximum adjust ernal RGB signals under I ² C-bus control, ss 02 _{Hex} (bit resolution 1.5% of maximum BF _{Hex} for maximum contrast 22 _{Hex} for nominal contrast 20 _{Hex} for minimum contrast contrast below maximum s adjust ernal RGB signals under I ² C-bus control, ss 00 _{Hex} (bit resolution 1.5% of maximum BF _{Hex} for maximum s adjust ernal RGB signals under I ² C-bus control, ss 00 _{Hex} (bit resolution 1.5% of maximum BF _{Hex} for maximum brightness 26 _{Hex} for nominal brightness	saturation); at 23_{Hex} at 00_{Hex} ; f = 100 kHz contrast); at 22_{Hex} at 00_{Hex}		50		dB

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
White pot	entiometers, under I ² C-bus control,		!	I.		1
data byte 3 data byte 7	sses 04 _{Hex} (red), 05 _{Hex} (green) and 06 _{Hex} (b 3F _{Hex} for maximum gain 19 _{Hex} for nominal gain 00 _{Hex} for minimum gain	blue); note 4.				
ΔG_v	relative to nominal gain:					
	increase of gain	at 3F _{Hex}	-	50	-	%
	decrease of gain	at 00 _{Hex}	-	50	-	%
-	outs pins 24, 22 and 20 oing output signals; peak drive limiter set =	3F _{Hex}); note 5.				
V _{o(b-w)}	nominal output signal amplitudes (black-to-white value)		-	2	-	V
	maximum output signal amplitudes (black-to-white value)		3.0	-	-	V
ΔVo	spread between RGB output signals		-	-	10	%
Vo	minimum output voltages		-	-	0.8	V
	maximum output voltages		6.8	-	-	V
V _{24,22,20}	voltage of cut-off measurement line = voltage during ultra-black	BCOF = 1 (output clamping)	2.3	2.5	2.7	V
l _{int}	internal current sources		-	5.0	-	mA
R _o	output resistance		-	20	-	Ω
Frequency	y response				·	
d	frequency response of Y path (from pin 8 to pins 24, 22, 20)	f = 10 MHz	-	-	3	dB
	frequency response of CD path (from pins 7 to 24 and 6 to 20)	f = 8 MHz	-	-	3	dB
	frequency response of RGB ₁ path (from pins 10 to 24, 11 to 22 and 12 to 20)	f = 10 MHz	-	-	3	dB
	frequency response of RGB ₂ path (from pins 2 to 24, 3 to 22 and 4 to 20)	f = 10 MHz	-	-	3	dB
Sandcast	le pulse detector (control bit SC5 = 0)					
three level	; notes 6 and 7					
V ₁₄	required voltage range					
	for H and V blanking pulses		2.0	2.5	3.0	V
	for H pulses (line count)		4.0	4.5	5.0	V
	for burst key pulses (clamping)		7.6	_	V _P +5.8	V

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
	le pulse detector (control bit SC5 = 1) notes 6 and 7			1		_
V ₁₄	required voltage range for H and V blanking pulses		2.0	2.5	3.0	V
	for burst key pulses		4.0	4.5	V _P +5.8	V
Sandcast	le pulse detector		4.0	4.0	VP+0.0	V
	output current	V ₁₄ = 0 V	_	_	-100	μA
t _d	leading edge delay of the clamping pulse	v ₁₄ = 0 v		1.5	-100	μs
				1.5		μο
VFB (note		for LOW		1	2.5	V
V ₁₈	vertical flyback pulse	for LOW	-	-	2.5	V
	internel velte ne	for HIGH	4.5	-	-	V
	internal voltage	pin 18 open-circuit; note 8	-	5.0	-	V
I ₁₈	input current		-	-	5	μA
Average b	beam current limiting (note 9)					
V _{c(15)}	contrast reduction starting voltage		_	4.0	_	V
$\Delta V_{c(15)}$	voltage difference for full contrast reduction		-	-2.0	-	V
V _{br(15)}	brightness reduction starting voltage		_	2.5	_	V
$\Delta V_{br(15)}$	voltage difference for full brightness reduction		-	-1.6	_	V
Peak drive	e limiting voltage (note 10)					
internal pe	ak drive limiting level (V _{pdl}) acts on RGB out	tputs				
	ontrol, sub-address 0A _{Hex}					
V _{20/22/24}	level for minimum RGB outputs	at byte 00 _{Hex}	_	-	3.0	V
	level for maximum RGB outputs	at byte 3F _{Hex}	7.0	-	_	V
I ₁₆	charge current		_	-1	_	μA
	discharge current	during peak white	_	5	_	mA
V ₁₆	internal voltage limitation		4.5	-	_	V
V _{c(16)}	contrast reduction starting voltage		_	4.0	_	V
$\Delta V_{c(16)}$	voltage difference for full contrast reduction		-	-2.0	-	V
V _{br(16)}	brightness reduction starting voltage		-	2.5	-	V
$\Delta V_{br(16)}$	voltage difference for full brightness reduction		-	-1.6	-	V

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Automation see Fig.9	c cut-off control (notes 7, 11, 12 and 13)	-				
V ₁₉	external voltage		-	-	V _P - 1.4	V
I ₁₉	output current		_	-	-60	μA
	input current		150	-	_	μA
	additional input current	switch-on delay 1	-	0.5	-	mA
V _{24,22,20}	monitor pulse amplitude (under I ² C-bus control, sub-address 0A _{Hex})	switch-on delay 1; note 12	-	V _{pdl} - 1.0	_	V
V ₁₉	voltage threshold for picture tube cathode warm-up	switch-on delay 1	-	4.5	-	V
	internally controlled voltage (V _{REF})	during leakage measurement period	-	2.7	_	V
ΔV_{19}	voltage difference between V_{MEAS} (cut-off measurement voltage) and V_{REF}		-	1.0	-	V
Cut-off st	orage			•	•	
I _{21/23/25}	charge and discharge currents	during cut-off measurement lines	-	±0.3	-	mA
	current	outside measurement	_	-	±0.1	μA
Leakage s	storage			•		
I ₁₇	charge and discharge currents	during leakage measurement period	-	±0.4	-	mA
	current	outside measurement	_	-	±0.1	μA
V ₁₇	threshold voltage for reset to switch-on state		-	2.5	-	V
under I ² C- data byte 3 data byte 2	r ol (note 14) bus control, sub-address 03 _{Hex} 3F _{Hex} for maximum voltage 20 _{Hex} for nominal voltage 00 _{Hex} for minimum voltage		•			
V ₂₆	output voltage	at byte 3F _{Hex}	4.8	-	-	V
		at byte 20 _{Hex}	-	3.0	-	V
		at byte 00 _{Hex}	-	-	1.2	V
l _{int}	current of the internal current source at pin 26		500	-	_	μA

TDA4685

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
l ² C-bus re	ceiver clock SCL (pin 28)		I	1		
f _{SCL}	input frequency range		0	-	100	kHz
V _{IL}	LOW level input voltage		_	-	1.5	V
V _{IH}	HIGH level input voltage		3.0	-	6.0	V
IIL	LOW level input current		_	-	-10	μA
I _{IH}	HIGH level input current		_	-	10	μA
t _d	pulse delay time LOW		4.7	-	-	μs
	pulse delay time HIGH		4.0	-	-	μs
t _r	rise time		_	-	1.0	μs
t _f	fall time		_	-	0.3	μs
l ² C-bus re	ceiver data input/output SDA (pin 27)		·		·	
V _{IL}	LOW level input voltage		-	-	1.5	V
V _{IH}	HIGH level input voltage		3.0	-	6.0	V
IIL	LOW level input current		_	-	-10	μA
I _{IH}	HIGH level input current		_	-	10	μA
I _{OL}	LOW level output current		3.0	-	_	mA
t _r	rise time		_	-	1.0	μs
t _f	fall time		_	-	0.3	μs
t _{SU;DAT}	data set-up time		0.25	_	-	μs

Notes to the characteristics

- 1. The values of the -(B-Y) and -(R-Y) colour difference input signals are for a 75% colour-bar signal.
- 2. The pins are capacitively coupled to a low ohmic source, with a recommended maximum output impedance of 600 Ω.
- 3. PAL/SECAM signals are matrixed by the equation: V_{G-Y} =– $0.51V_{R-Y}$ $0.19V_{B-Y}$

NTSC signals are matrixed by the equations (hue phase shift of -5 degrees): $V_{R-Y^*} = 1.57V_{R-Y} - 0.41V_{B-Y}$; $V_{G-Y^*} = -0.43V_{R-Y} - 0.11V_{B-Y}$; $V_{B-Y^*} = V_{B-Y}$ In the matrix equations: V_{R-Y} and V_{B-Y} are conventional PAL demodulation axes and amplitudes at the output of the NTSC demodulator. $V_{R-Y^*} = V_{R-Y^*} = V_{R-Y^*}$

NTSC demodulator. V_{G-Y}^* , V_{R-Y}^* and V_{B-Y}^* are the NTSC-modified colour difference signals; this is equivalent to the following demodulator axes and amplification factors:

	NTSC	PAL
(B-Y)* demodulator axis	0°	0°
(R-Y)* demodulator axis	115°	90°
(R–Y)* amplification factor	1.97	1.14
(B-Y)* amplification factor	2.03	2.03

 $V_{G-Y}{}^{*} = -0.27 V_{R-Y}{}^{*} - 0.22 V_{B-Y}{}^{*}.$

4. The white potentiometers affect the amplitudes of the RGB output signals.

5. The RGB outputs at pins 24, 22 and 20 are emitter followers with current sources.

- Sandcastle pulses are compared with internal threshold voltages independent of V_P. The threshold voltages separate the components of the sandcastle pulse. The particular component is generated when the voltage on pin 14 exceeds the defined internal threshold voltage. The internal threshold voltages (control bit SC5 = 0) are:
 - 1.5 V for horizontal and vertical blanking pulses (H and V blanking pulses),
 - 3.5 V for horizontal pulses,
 - 6.5 V for the burst key pulse.
 - The internal threshold voltages, control bit SC5 = 1, are:
 - 1.5 V for horizontal and vertical blanking pulses,
 - 3.5 V for the burst key pulse.
- 7. Vertical signal blanking is determined by the vertical component of the sandcastle pulse. The leakage and the RGB cut-off measurement lines are positioned in the first four complete lines after the end of the vertical component. In this case, the RGB output signals are blanked until the end of the last measurement line; see Fig 9(a). If an extra vertical flyback pulse VFB is applied to pin 18, the four measurement lines start in the first complete line after the end of the VFB pulse; see Fig 9(b). In this case, the output signals are blanked either until the end of the last measurement line or until the end of the vertical component of the sandcastle pulse, according to which occurs last.
- 8. If no VFB pulse is applied, pin 18 can be left open-circuit or connected to V_P. If pin 18 is always LOW neither automatic cut-off control nor output clamping can happen.
- 9. Average beam current limiting reduces the contrast, at minimum contrast it reduces the brightness.
- 10. Peak drive limiting reduces the RGB outputs by reducing the contrast, at minimum contrast it reduces the brightness. The maximum RGB outputs are determined via the I²C-bus under sub-address 0A_{Hex}. When an RGB output exceeds the maximum voltage, peak drive limiting is delayed by one horizontal line.
- 11. During leakage current measurement, the RGB channels are blanked to ultra-black level. During cut-off measurement one channel is set to the measurement pulse level, the other channels are blanked to ultra-black. Since the brightness adjust shifts the colour signal relative to the black level, the brightness adjust is disabled during the vertical blanking interval (see Fig.8 and Fig.9).
- 12. During picture cathode warm-up (first switch-on delay) the RGB outputs (pins 24, 22 and 20) are blanked to the ultra-black level during line scan. During the vertical blanking interval a white-level monitor pulse is fed out on the RGB outputs and the cathode currents are measured. When the voltage threshold on pin 19 is greater than 4.5 V, the monitor pulse is switched off and cut-off control is activated (second switch-on delay). As soon as cut-off control stabilizes, RGB output blanking is removed.
- 13. The cut-off measurement level range at the RGB outputs is 1 to 5 V. The recommended value is 3 V.
- 14. The hue control output at pin 26 is an emitter follower with current source.

Video processor with automatic cut-off control





seating plane

Video processor with automatic cut-off control

PACKAGE OUTLINE

DIP28: plastic dual in-line package; 28 leads (600 mil)





SOT117-1

051G05

MO-015AH

TDA4685

SOT117-1

Z ⁽¹⁾

max.

1.7

0.067

92-11-17 95-01-14

 \square

SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact

with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

DEFINITIONS

Data sheet status		
Objective specification	This data sheet contains target or goal specifications for product development.	
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.	
Product specification	This data sheet contains final product specifications.	
Limiting values		
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.		
Application information		
Where application information is given, it is advisory and does not form part of the specification.		

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